

CUSTOMER ADVISORY

ADV1908

Conversion to Intel Packing Methodology (Change in Humidity Indicator Card Placement and Desiccant Quantity in Tray, Tape & Reel, and Tube Packed Products)

Change Description:









Intel® Programmable Solutions Group (“Intel PSG”, formerly Altera) is notifying customers of an update to the packing method. *This is the same change described in Intel PCN 116896.*



To address the marginality of coloration displayed on the Humidity Indicator Card (HIC) of desiccant packed products, Intel will be modifying the packing to:

- Relocate the HIC and add a second desiccant pouch to Tray packed products that are shipped in a Half-Height Intermediate Box (i.e. Half Stack), a Full Intermediate Box (i.e. Full Stack), and 13” Tape & Reel packed products.
- Relocate the HIC on Small I-box pack, Tube Pack and 7” Tape & Reel pack but retain the use of one desiccant pouch.

Table 1 below shows sample images for reference

Table 1: Packing Change

Packing Method	Change From	Change To	Description
Tray	 <p>PIN 1 Chamfer corner</p>		Tray using plastic shim with 2x Desiccant Pouches and HIC in the middle.
			Tray that will be bubble wrapped with 2x Desiccant Pouches and HIC in the middle.
Tube			Tube with single Desiccant Pouch beside HIC.
7-inch Tape & Reel Packed			7-inch Tape and Reel with single Desiccant Pouch on top and HIC moved to the side.

<p>13-inch Tape & Reel Packed</p>			<p>13-inch Tape and Reel with 2x Desiccant Pouches with HIC in the middle.</p>
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Additional Note

If any product is opened within 10 days of the seal date shown on the label and the HIC is Pink (Not passing), inspect the MBB for punctures, holes and verify the seal. If these are passing, then the product is safe to use.

Recommended Action

There is no change to the form, fit, or function of the product due to this change. Customers should, however, notify those at the customer site who open packaged materials to ensure they are aware of the change.

There will be a transition period where Intel will deplete current on-shelf material already packed with only a single desiccant pouch. Customers should expect to see a mix of packing options until packed materials with a single desiccant pouch are depleted.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected:

The change will apply to Intel PSG products packed with desiccant in Tray, Tube, and Tape & Reel media.

The list of affected OPNs can be downloaded in Excel form here:

<https://www.intel.com/content/dam/www/programmable/us/en/pdfs/literature/pcn/adv1908-opn-list.xlsx>

Reason for Change:

The purpose of this conversion is to standardize and align the packing methodology of PSG products to that of Intel.

Change Implementation

Table 4

Milestone	Date
Date Packing Conversion is in Effect	Now

Contact

For more information, please contact Sales or Customer Quality Engineering (CQE) in your region, or submit a Service Request at the [My Intel](#) support page.

Customer Notifications Subscription

Customers that have subscribed to Intel PSG's customer notification mailing list will receive the PCN document automatically via email.

If you would like to receive customer notifications by email, please subscribe to our customer notification mailing list at:

<https://www.intel.com/content/www/us/en/programmable/my-intel/mal-emailsub/technical-updates.html>

Revision History

Date	Rev	Description
07/19/2019	1.0.0	Initial Release

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